

## 2A, 400V - 600V ESD Capability Rectifier

### FEATURES

- High ESD capability
- Glass passivated chip junction
- Low forward voltage drop
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

### APPLICATIONS

- General purpose
- Polarity protection

### MECHANICAL DATA

- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.030g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_F$	2	A
$V_{RRM}$	400 - 600	V
$I_{FSM}$	40	A
$T_J \text{ MAX}$	175	°C
Package	Thin SMA	
Configuration	Single die	


**HALOGEN  
FREE**


Thin SMA



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	TSD2GAL	TSD2JAL	UNIT
Marking code on the device			D2GAL	D2JAL	
Repetitive peak reverse voltage		V <sub>RRM</sub>	400	600	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	280	420	V
Forward current		I <sub>F</sub>	2		A
Surge peak forward current single half sine-wave superimposed on rated load	t = 8.3ms	I <sub>FSM</sub>	40		A
	t = 1.0ms		130		
Junction temperature		T <sub>J</sub>	-40 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C

**THERMAL PERFORMANCE**

PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	15	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	75	°C/W
Junction-to-case thermal resistance	$R_{\theta JC}$	15	°C/W

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

**ELECTRICAL SPECIFICATIONS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 1\text{A}, T_J = 25^\circ\text{C}$	$V_F$	0.89	-	V
	$I_F = 2\text{A}, T_J = 25^\circ\text{C}$		0.94	1.1	V
	$I_F = 1\text{A}, T_J = 125^\circ\text{C}$		0.77	-	V
	$I_F = 2\text{A}, T_J = 125^\circ\text{C}$		0.83	-	V
Reverse current @ rated $V_R$ <sup>(2)</sup>	$T_J = 25^\circ\text{C}$	$I_R$	-	1	$\mu\text{A}$
	$T_J = 125^\circ\text{C}$		5	-	$\mu\text{A}$
Junction capacitance	1MHz, $V_R = 4.0\text{V}$	$C_J$	15	-	pF

**Notes:**

- Pulse test with  $PW = 0.3\text{ms}$
- Pulse test with  $PW = 30\text{ms}$

**IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE
AEC-Q101-001	Human body mode	$C=100\text{pF}, R=1.5\text{k}\Omega$	$V_c$	H3B	$\geq 8\text{kV}$
IEC 61000-4-2	Contact mode	$C=150\text{pF}, R=330\Omega$		x	$\geq 10\text{kV}$
	Air-discharge mode	$C=150\text{pF}, R=330\Omega$		4	$\geq 15\text{kV}$

**ORDERING INFORMATION**

ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
TSD2xAL	Thin SMA	14,000/ Tape & Reel

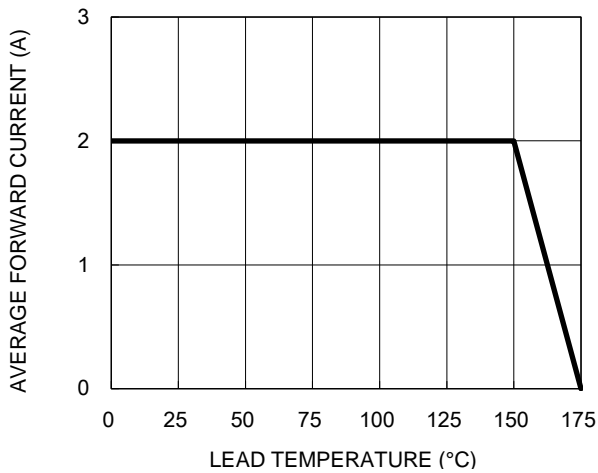
**Notes:**

- "x" defines voltage from 400V(TSD2GAL) to 600V(TSD2JAL)

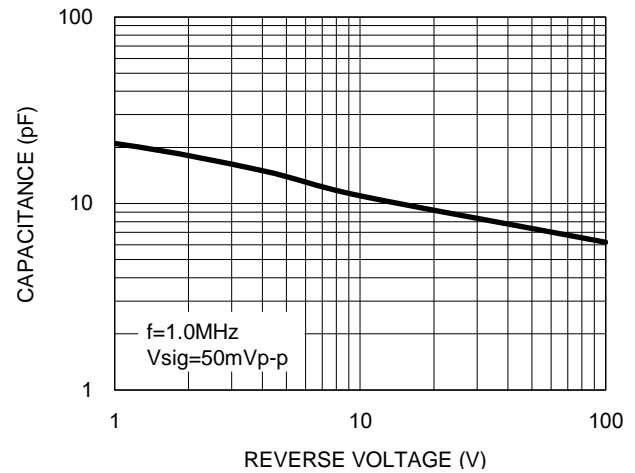
## CHARACTERISTICS CURVES

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

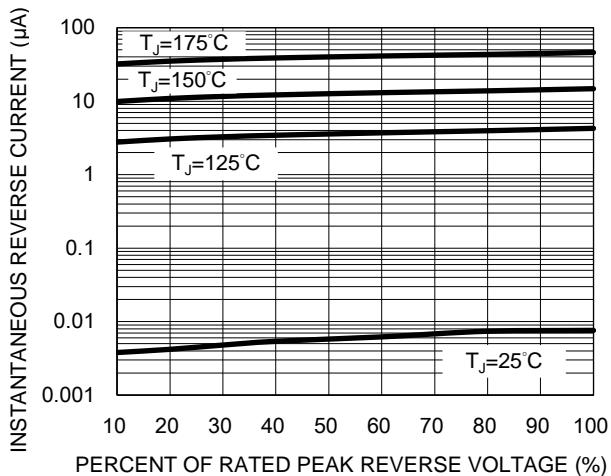
**Fig.1 Forward Current Derating Curve**



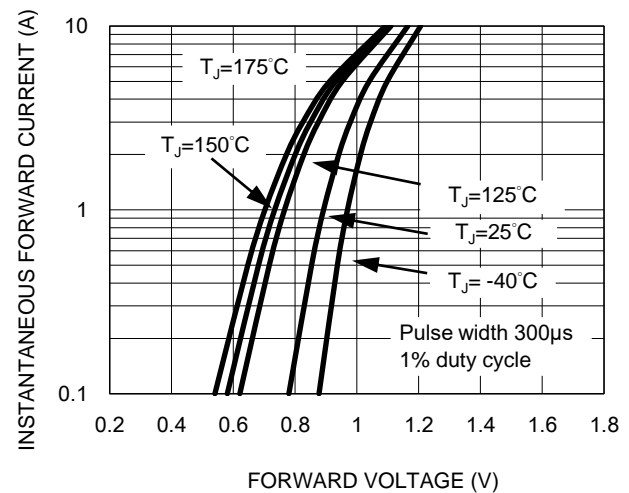
**Fig.2 Typical Junction Capacitance**



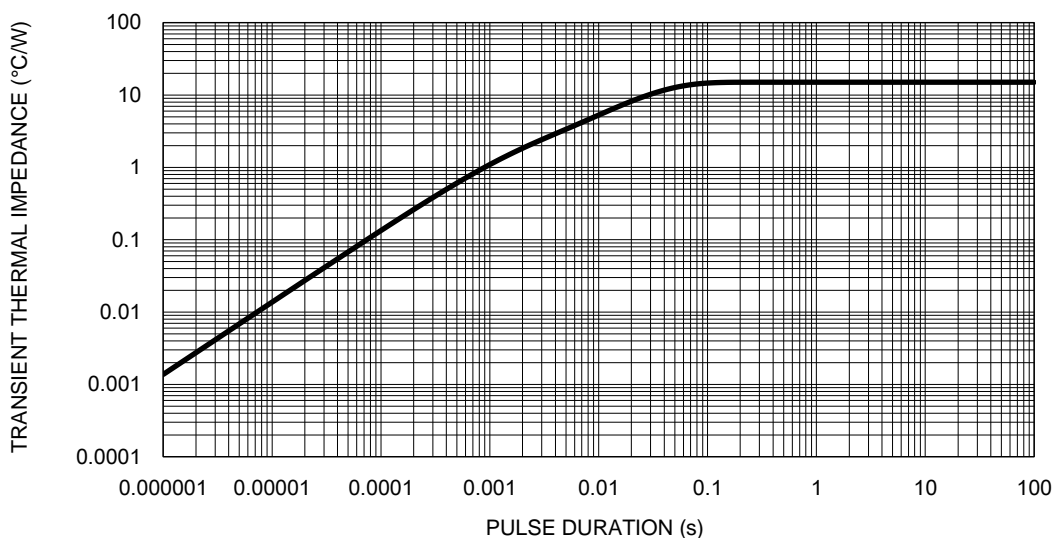
**Fig.3 Typical Reverse Characteristics**



**Fig.4 Typical Forward Characteristics**

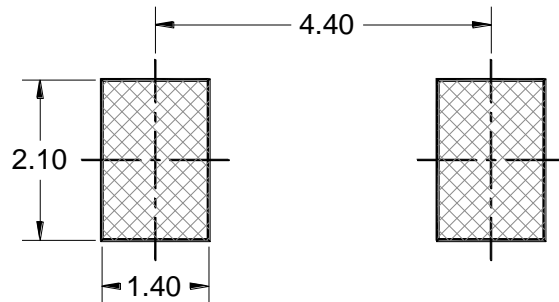
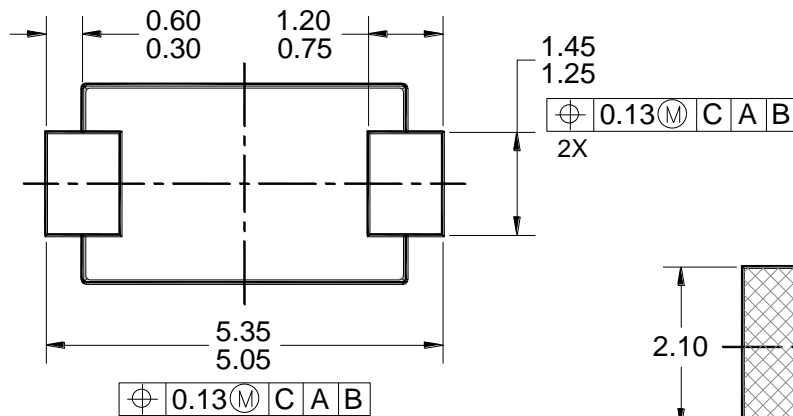
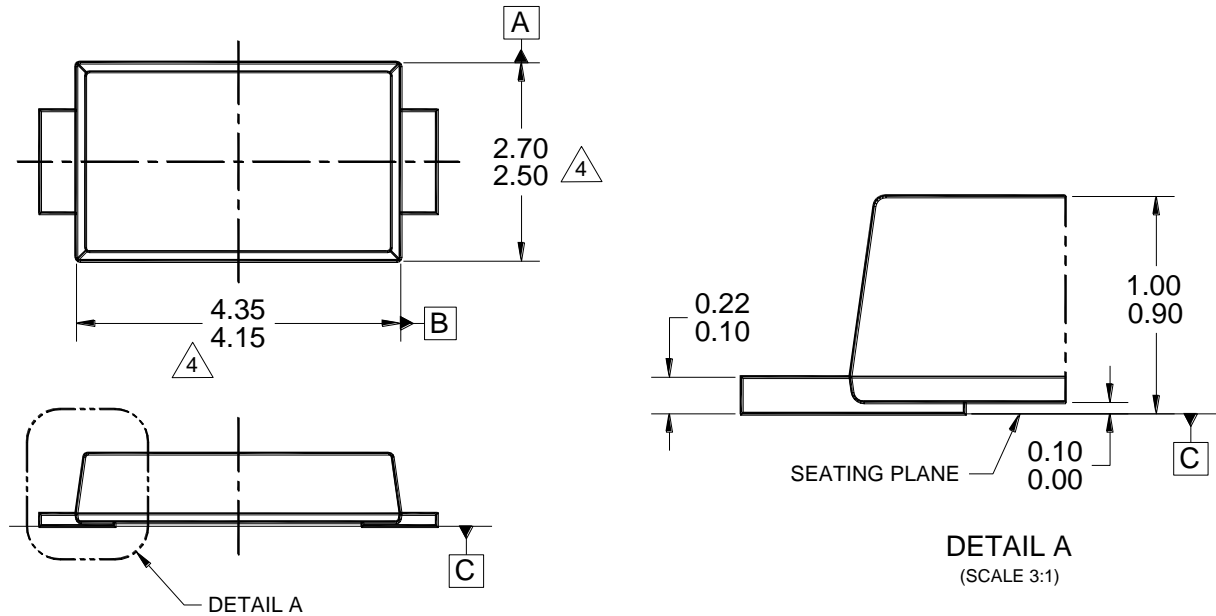


**Fig.5 Typical Transient Thermal Impedance**

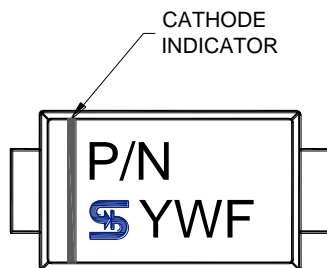


## PACKAGE OUTLINE DIMENSIONS

### Thin SMA



**SUGGESTED PAD LAYOUT**



**MARKING DIAGRAM**

P/N = MARKING CODE  
YWF = DATE CODE  
F = FACTORY CODE

### NOTES: UNLESS OTHERWISE SPECIFIED

- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- PACKAGE OUTLINE REFERENCE: JEDEC DO-221, VARIATION AC, ISSUE B.
- MODED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- SUGGESTED PAD LAYOUT IS FOR REFERENCE PURPOSE ONLY.
- DWG NO. REF: HQ2SD07-TSMA-074 REV A.

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